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Abstract

Method for connecting an integrated circuit to a substrate and corresponding circuit arrangement

The present invention provides a method for connecting an integrated circuit (5), in particular from a chip or a wafer or a hybrid, to a substrate (100), which has the following steps: provision of a package (1a'; 1b'; 1c') for the integrated circuit, which has a connection side (AS), on which there are provided a plurality of connection regions (150; 150, 150') for connection to the substrate (100); provision of a corresponding plurality of connection regions (110) on the substrate (100); provision of elevated contact regions (30; 35) on the connection regions (150; 150, 150') of the package (1a'; 1b'; 1c') and/or the connection regions (110) of the substrate (100); the elevated contact regions (30; 35) comprising a first group of contact regions (30) and a second group of contact regions (35); and creation of a connection of the package (1a'; 1b'; 1c') to the substrate (100) via the elevated contact regions (30; 35); the elevated contact regions (30; 35) being configured in such a way that the first group of contact regions (30) form a rigid connection and the second group of contact regions (35) form an elastic connection between the package (1a'; 1b'; 1c') and the substrate (100). The invention likewise provides a corresponding circuit arrangement.

Fig. 1b

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